

Technical Disclosure Commons

Defensive Publications Series

January 2022

FLOATING WIRELESS CHARGING MODULE

HP INC

Follow this and additional works at: https://www.tdcommons.org/dpubs_series

Recommended Citation

INC, HP, "FLOATING WIRELESS CHARGING MODULE", Technical Disclosure Commons, (January 31, 2022)
https://www.tdcommons.org/dpubs_series/4875



This work is licensed under a [Creative Commons Attribution 4.0 License](https://creativecommons.org/licenses/by/4.0/).

This Article is brought to you for free and open access by Technical Disclosure Commons. It has been accepted for inclusion in Defensive Publications Series by an authorized administrator of Technical Disclosure Commons.

Floating Wireless Charging Module

This disclosure relates to the field of operating the wireless charging that integrated in a device, such as the stand of display or AIO product. The mechanism allows the end user to lie the mobile phone on the module with effective charging no matter if the rear camera module sticking out of its back-cover surface.

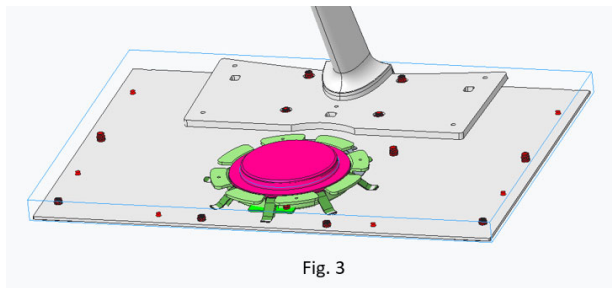
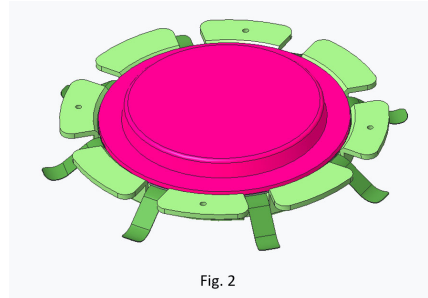
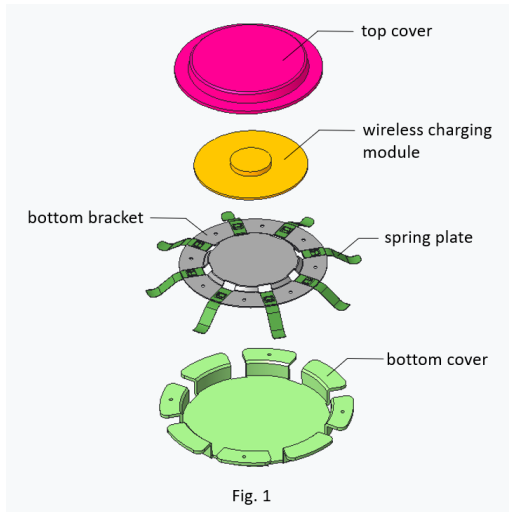
Nowadays in the market, the rear camera module of a mobile phone will protrude out of its rear cover. That design will cause the mobile phone to not be in complete contact with the wireless charging module and affect the charging quality.

The mechanism composes of a cover, wireless charging module, bottom bracket, spring plates and bottom cover (Fig. 1). And the sequence to assemble them is:

- a. Clamp the spring places on the bottom bracket.
- b. Place the sub-assy bottom bracket on the bottom cover.
- c. Place the wireless charging module on the sub-assy bottom bracket.
- d. Assemble the top cover on the charging module.

The whole module assembly (Fig. 2) can then be integrated in a device, such as the stand of an AIO or display (Fig. 3).

While placing a mobile phone the independent wireless charging module, the spring plates of the module will accommodate the gap/angle with the mobile phone (Fig. 4 and Fig. 5).



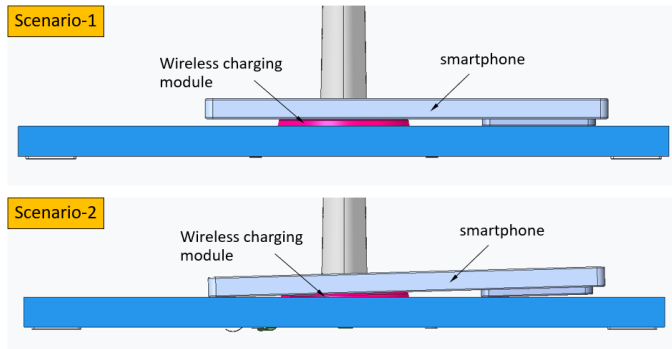


Fig. 4

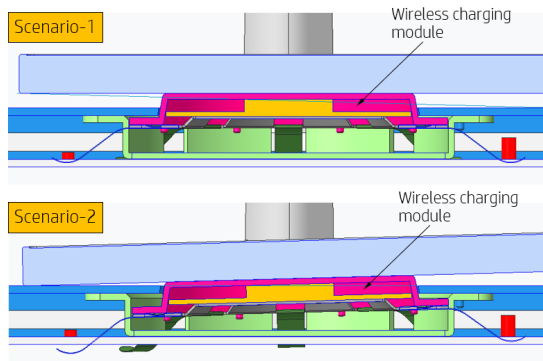


Fig. 5

Disclosed by Patrick Chung, HP Inc.